



3D Packaging & Integration North America TC Chapter

NA Standards Fall Meetings 2023

Thursday, November 9

SEMI Headquarters, Milpitas, California/USA

13:00–14:00 Pacific (OVTCCM)

AGENDA

	Time
1 Welcome/Call to Order	13:00
1.1 Please log into www.svm.semi.org for voting	
1.2 Required Elements (Membership Requirements, Antitrust and Intellectual Property Reminders, and Effective Meeting Guidelines)	
1.3 Agenda Review	
1.4 Introductions	
2 Liaison Reports	13:10
2.1 Japan TC Chapter	
2.2 Taiwan TC Chapter (<i>no update</i>)	
3 Staff Report	13:15
4 Review of Previous Meeting Minutes	13:20
5 Ballot Review	13:25
5.1 Document 7101 — Revision to SEMI 3D5-0314 (Reapproved 1218), Guide for Metrology Techniques to be Used in Measurement of Geometrical Parameters of Through-Silicon Vias (TSVs) in 3DS-IC Structures	
6 Task Force Updates	13:35
6.1 3DP&I Bonded Wafer Stacks Task Force	
6.2 3DP&I Inspection & Metrology Task Force	
6.3 Panel Level Packaging (PLP) Panel Task Force (<i>did not meet</i>)	



	Time
7 Old Business	13:45
7.1 Five-Year Review	
8 New Business	13:50
9 Action Item Review	13:55
10 Next Meeting and Adjournment	14:00
10.1 The next meeting is tentatively scheduled for the week of March 25-28, in conjunction with NA Standards Spring Meetings 2024. Schedule details TBD. Please check www.semi.org/standards for updates.	

Tentative Schedule:

- Thursday, March 28
 - TBD, Panel Level Packaging (PLP) Panel TF
 - 11:00-12:00, Joint 3DP&I Bonded Wafer Stacks Task Force, and 3DP&I Inspection & Metrology Task Force
 - 13:00-14:00, 3DP&I NA TC Chapter

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STANDARDS VIRTUAL MEETING INFORMATION LINK

<https://www.semi.org/en/semi-standards-fall-2023-meetings-virtual-information>

NOTE:

Standards meetings are open to all, but you must be a SEMI Standards Program Member to attend.

If you are not a member, please register for the International SEMI Standards Program here:

<https://www.semi.org/standardsmembership>